

# mini PFE 100 / 200

Precision physical clean cell



Equipment capable of continuous automatic processing of the top and bottom surfaces of strip-shaped workpieces

Small cell using wide gun is used for electric industry such as printed-circuit boards or semiconductors. By processing to both sides uniformly, it can apply for rod shape and sheet shape. Applicable for ceramic and Cu plate.

## Feature

- Functions are integrated, but its wet-blasting processing quality remains as is. Newly developed cell as a small sized and cost-saving purpose.
- Compact blasting and water rinsing parts make the maintenance for actuators easy; simply opening a conveyor cover. Also the wide gun and the pump as principal parts, still hold the original high durability.
- Lineup of 2 types (mini PFE 100/200) according to the size of workpiece.

## Spec

### mini PFE 100

<b>Size</b>	1200(W)×1250(D)×1600(H)mm
<b>Work size</b>	Width : 20-100mm Length : 100-250mm Thickness : 0.1-1.5mm
<b>Conveyor transportation speed</b>	0.1□3.0m/min
<b>Gun</b>	Wide Gun 110mm One each for top and bottom
<b>Power supply</b>	AC200V, 50/60Hz, 3 phases
<b>Power consumption</b>	About 2.6kW (Total rated apparent power of all the equipment)
<b>Air supply pressure</b>	0.5MPa-0.7MPa
<b>Air consumption</b>	4.1m <sup>3</sup> /min (NTP at 0.25 MPa of preset blast air pressure)

### mini PFE 200

<b>Size</b>	1200(W)×1650(D)×1650(H)mm
<b>Work size</b>	Width : 20-200mm Length : 100-250mm Thickness : 0.1-1.5mm
<b>Conveyor transportation speed</b>	0.1□3.0m/min
<b>Gun</b>	Wide Gun 220mm One each for top and bottom
<b>Power supply</b>	AC200V, 50/60Hz, 3 phases
<b>Power consumption</b>	About 4.3kW (Total rated apparent power of all the equipment)
<b>Air supply pressure</b>	0.5MPa-0.7MPa
<b>Air consumption</b>	7.7m <sup>3</sup> /min (NTP at 0.25 MPa of preset blast air pressure)

## Related pages

## Related applications



[Pretreatment for plating to remove burrs without damaging the semiconductors \(deflashing\)](#)



[Overmolded resin removal method that drastically reduces damage to buried LED chips](#)



[Processing method to remove thin burrs \(flash-burrs\) without damaging the LED package](#)